SEMICONDUCTOR MARKET SOLUTIONS

DISCRETE COMPONENTS

DIE ATTACH: CONDUCTIVE SOLDER

PRODUCT	DESCRIPTION	APPLICATION	VISCOSITY, cPs	ALLOY	REFLOW	CLEANABILITY	VOID LEVELS	IPC/J-STD-004 CLASSIFICATION
DA100™ (Solder)	Flux designed for solder die attach paste applications.	Dispensing	250,000	High Pb	Forming Gas	Excellent	Very Low	ROL0

DIE ATTACH ADHESIVES: NON-CONDUCTIVE

PRODUCT	DESCRIPTION	FINISH (Cu, Ag, Au)	MRT	ELECTRICAL CONDUCTIVITY	DISPENSABILITY	CURE SCHEDULE	THERMAL CONDUCTIVITY, W/mK
QMI536HT™	High thermal version of QMI536™, ideal for mixed stacked die applications. Non-die damaging filler.	Ag, Au	L3 - 260	1 x 10^{13}	Excellent	! 8 sec @ 150°C (*Skip*Cure™) 15 min @ 150°C (Oven)	0.9
QMI547™	Non-conductive paste for leadframe applications.	Au, Ag, Cu	L3 - 260	1 x 10^{13}	Excellent	! 8 sec @ 150°C (*Skip*Cure™) 15 min @ 150°C (Oven)	0.3

ELECTRONIC MOLDING COMPOUNDS

PRODUCT	DESCRIPTION	CONVENTIONAL MOLD	SPIRAL FLOW in, @ 177°C	Tg, °C	CTE_{a1}, ppm/°C	CTE_{a2}, ppm/°C	CURE TIME @ 177°C	FLEXURAL STRENGTH, psi	FLEXURAL MODULUS, psi	LASER MARKABLE
GR2220™	Black/conventional molding of MnO caps.	Conv	40	162	13	60	30 - 45 sec	18,500	2.4 x 10^{6}	N
GR2310™	Gold/non-halogenated molding powder, tantalum and ceramic capacitors, leaded or surface-mounted sensors.	Auto/Conv	27	166	22	75	30 - 45 sec	20,500	2.1 x 10^{6}	Y
GR2710™	Gold/low stress/non-flame retarded molding powder, tantalum and ceramic capacitors, leaded or surface-mounted sensors.	Auto/Conv	35	161	13	45	45 - 60 sec	19,000	2.6 x 10^{6}	Y
GR2811™	Gold/thin wall-crack resistant, low stress, fast cycle time.	Auto/Conv	34	162	13	45	30 - 45 sec	20,000	2.9 x 10^{6}	Y
MG40FS™	Black/conventional molding of SMD and SIP networks. Gold version MG40F-0526™ available.	Conv	35	160	20	75	60 - 90 sec	19,000	2.4 x 10^{6}	N

ENCAPSULANTS

PRODUCT	DESCRIPTION	RECOMMENDED CURE	FLOW SPEED	VISCOSITY 25°C, cPs	Tg, °C	CTE_{a1}, ppm/°C	% FILLER
FP0087™	Low stress fill for potting automated sensor and diodes, high Tg.	1 hr @ 125°C + 1 hr @ 180°C	High	20,000	175	18	76